PRODUCT END-OF-LIFE DISASSEMBLY INSTRUCTIONS

Product Category: Personal Computers
Marketing Name / Model
XBOOK B15

Purpose: The document is intended for use by end-of-life recyclers. It provides the instructions for the disassembly of Lanix products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	**Notes**	**Quantity of items included in product**
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	Mother Board, SSD, RAM,	3
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries		
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-Ion battery	1
Mercury-containing components		
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Notebook Display	1
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords	External Power Supply	1
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner		
Components and waste containing asbestos		

Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where component and materials requiring selective treatment can be removed.

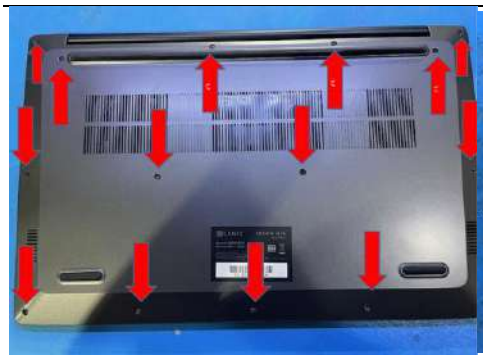
Tool Description	Tool Size (If applicable)
#1 Screwdriver	PHILLIPS PH1

3.0 Product Disassembly Process

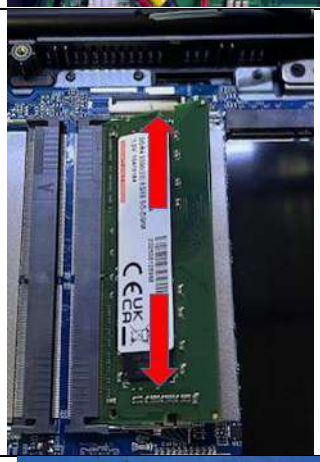
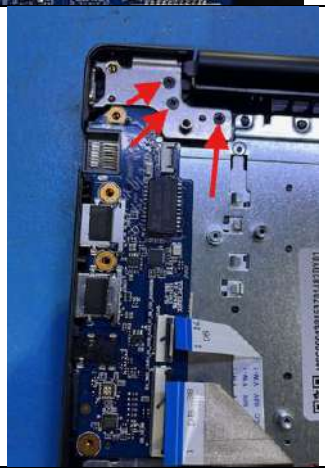
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

1. Remove the screws from the bottom cover.
2. Remove the bottom cover.
3. Remove the screws securing the CPU Cooler and remove the CPU Cooler.
4. Remove the screws securing the fan and remove the fan.
5. Disconnect the battery from the motherboard.
6. Remove the screws securing the battery and remove the battery.
7. Remove the screws securing the motherboard.
8. Disconnect the LCD cable, the battery cable, the keyboard cable and all the cables connected to the motherboard.
9. Remove the motherboard.
10. Remove the screws securing the I/O board and remove the I/O board.
11. Remove the screw securing the SSD and remove the SSD.
12. Remove the memory module.
13. Remove the screws securing the display hinges to the chassis.
14. Lift the display assembly upward to detach it from the unit.
15. Detach the adhesive plastic bezel surrounding the screen to access and remove the display panel.

3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit.

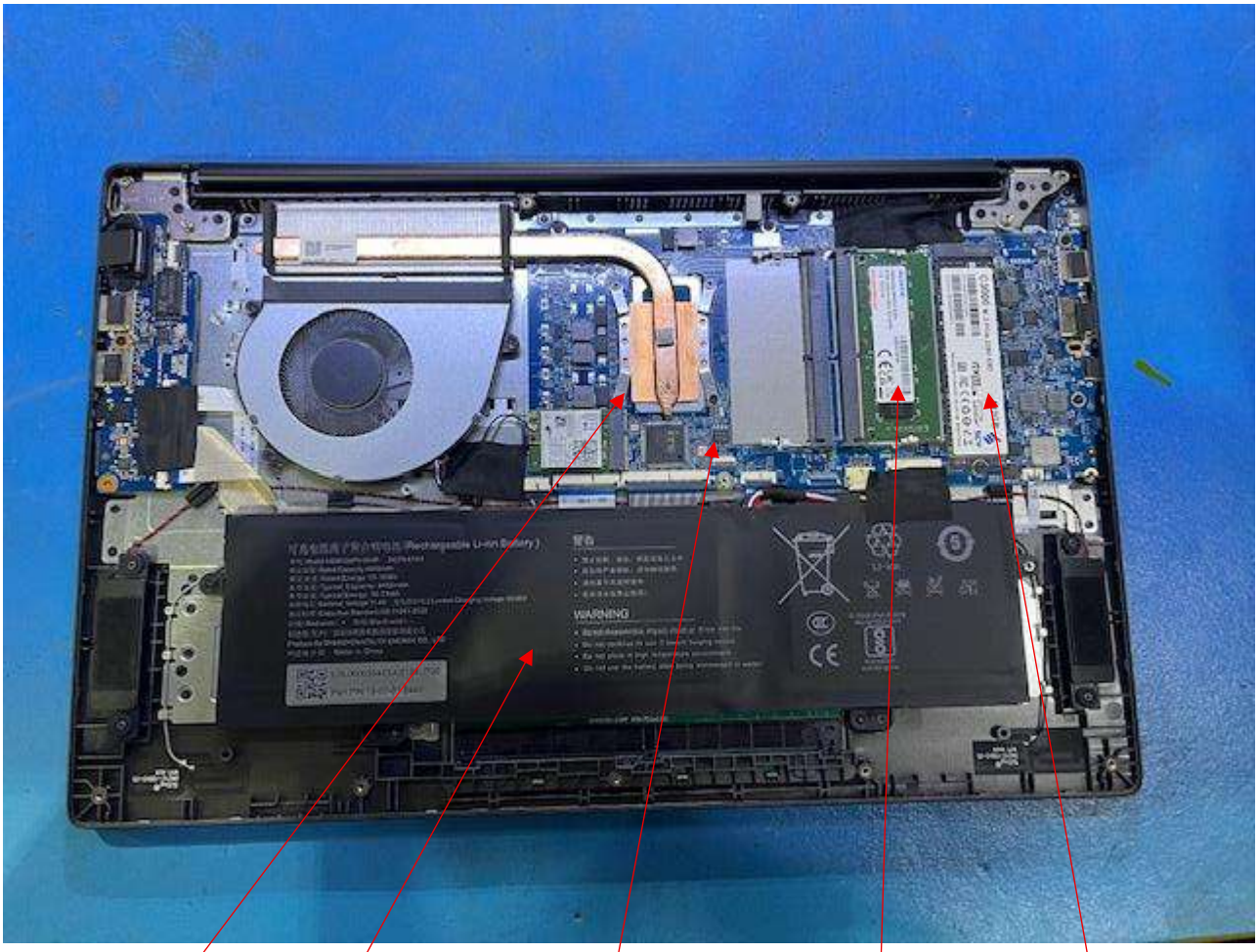
1. Remove the screws from the bottom cover with Phillips PH1 and remove the cover	  
2. Remove the screws securing the CPU Cooler and remove the CPU Cooler with Phillips PH1	  

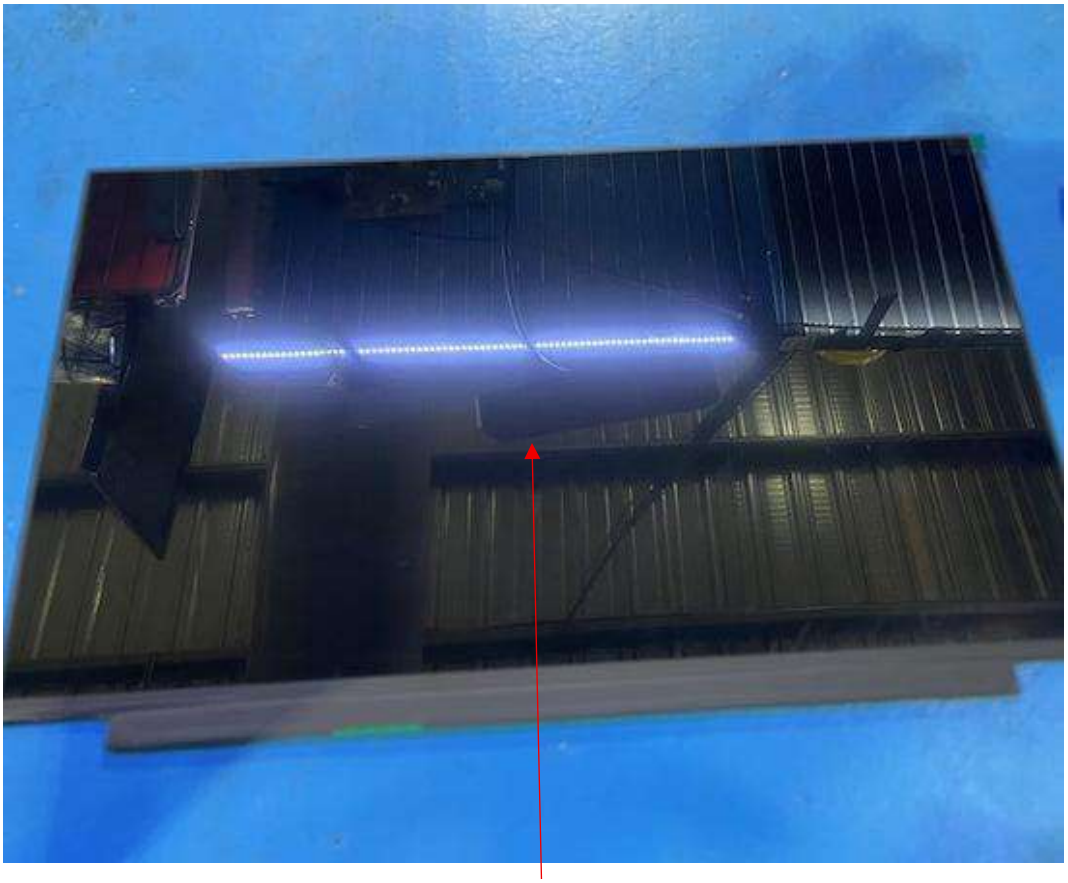
3. Remove the screws securing the fan and remove the fan with Phillips PH1	 
4. Disconnect and remove the screws securing the battery with Phillips PH1	 
5. Remove the screws securing the motherboard, disconnect all the cables connected to the motherboard and remove the motherboard.	 

6. Remove the screws securing the I/O board and remove the I/O board	 
7. Removed SDD with Phillips PH1	
8. Removed RAM and RTC battery tool less	
9. Remove the screws securing the display hinges to the chassis with Phillips PH1.	

10.Lift the display assembly upward to detach it from the unit. Detach the adhesive plastic bezel surrounding the screen to access and remove the display panel.	   

3.2 Location of components requiring selective treatment.





LCD

External Power Supply